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(WO/2004/068242) RESIST COMPOSITION

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Title: (EN) RESIST COMPOSITION
(JA) レジスト組成物

Abstract: (EN) A resist composition for use in an immersion lithography process which satisfies a specific parameter; a positive resist composition which comprises a resin component (A) having a dissolution-suppressing group being dissociated by an acid and thus exhibiting enhanced solubility in an alkali by the action of an acid, an acid generating component (B) and an organic solvent (C), wherein the (A) component (a1) has a constituting unit derived from a (meth)acrylate ester having a dissolution-suppressing group being dissociated by an acid and (a0) has no organic constituting unit (a0-1) containing an anhydride of a dicarboxylic acid and no organic constituting unit (a0-2) containing a phenolic hydroxyl group; and a method for forming a resist pattern which comprises using the above resist composition. The resist composition is resistant to a solvent used in an immersion lithography process, and also is excellent in sensitivity and in the form of a resist pattern profile.

(JA) イマージョンリソグラフィ工程において使用される溶媒に対して安定であり、感度、レジストパターンプロファイル形状に優れる、レジスト組成物、及びこれらレジスト組成物を用いるレジストパターンの形成方法が提供される。所定のパラメータに該当するレジスト組成物、または酸解離性溶解抑制基を有し、酸の作用によりアルカリ可溶性が増大する樹脂成分(A)と、酸発生剤成分(B)と、有機溶剤(C)とを含み、前記(A)成分は、(a1)酸解離性溶解抑制基を有する(メタ)アクリル酸エステルから誘導される構成単位を有し、かつ(a0)(a0-1)ジカルボン酸の無水物含有構成単位及び(a0-2)フェノール性水酸基含有構成単位を有さないポジ型レジスト組成物。

Designated States: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, VZ, VC, VN, YU, ZA, ZM, ZW.
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